A PROCESS OF FORMING METAL SURFACES COMPATIBLE WITH A WIRE BONDING AND SEMICONDUCTOR INTEGRATED CIRCUITS MANUFACTURED BY THE PROCESS

Abstract of the Disclosure

The present invention relates to the structure and process of forming metal surfaces on the bare metal interconnect of a semiconductor chip. The metal chip comprises metal interconnect formed on a semiconductor substrate and at least a portion of the metal interconnect is exposed to the environment. In one aspect of the invention, the process comprises applying a noble metal on the exposed portion of the metal interconnect and performing a chemical process that causes a layer of the noble metal to convert into a bondable layer compatible with a conventional wire bonding. The process also comprises bonding a metal wire to the bondable layer.

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